

# SEMIPACK® 1

### **Thyristor Modules**

#### **SKKT 58/16 E**

#### **Features**

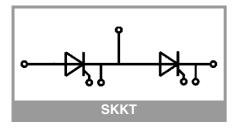
- Heat transfer through aluminium oxide ceramic isolated metal baseplate
- UL recognized, file no. E63532

#### **Typical Applications\***

- DC motor control (e. g. for machine tools)
- AC motor soft starters
- Temperature control (e. g. for ovens, chemical processes)
- Professional light dimming (studios, theaters)

Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit				
Chip				,				
I <sub>T(AV)</sub>	sinus 180°	T <sub>c</sub> = 85 °C	55	Α				
		T <sub>c</sub> = 100 °C	41	Α				
I <sub>TRMS</sub>	continuous operation		90	Α				
I <sub>TSM</sub>	10 ms	T <sub>j</sub> = 25 °C	1500	Α				
		T <sub>j</sub> = 130 °C	1200	Α				
i <sup>2</sup> t	10 ms	T <sub>j</sub> = 25 °C	11250	A <sup>2</sup> s				
	101113	T <sub>j</sub> = 130 °C	7200	A <sup>2</sup> s				
$V_{RSM}$			1700	V				
$V_{RRM}$			1600	V				
$V_{DRM}$			1600	V				
(di/dt) <sub>cr</sub>	T <sub>j</sub> = 130 °C		140	A/μs				
(dv/dt) <sub>cr</sub>	T <sub>j</sub> = 130 °C		1000	V/µs				
Tj			-40 130	°C				
Module				-				
T <sub>stg</sub>			-40 125	°C				
V <sub>isol</sub>	a.c.; 50 Hz; r.m.s.	1 min	3000	V				
	a.c., 50 112, 1.111.5.	1 s	3600	V				

Characte	ristics					
Symbol	Conditions	min.	typ.	max.	Unit	
Chip			•			
V <sub>T</sub>	$T_j = 25 ^{\circ}\text{C}, I_T = 180 \text{A}$			1.5	1.75	V
$V_{T(TO)}$	T <sub>j</sub> = 130 °C			0.85	1	V
r <sub>T</sub>	T <sub>j</sub> = 130 °C			4.00	4.8	mΩ
$I_{DD};I_{RD}$	$T_j = 130 ^{\circ}\text{C},  V_{DD} = V_{DRM};  V_{RD} = V_{RRM}$				20	mA
t <sub>gd</sub>	$T_j = 25 ^{\circ}\text{C},  I_G = 1  \text{A},  di_G/dt = 1  \text{A}/\mu\text{s}$			1		μs
t <sub>gr</sub>	$V_D = 0.67 * V_{DRM}$			2		μs
tq	T <sub>j</sub> = 130 °C			170		μs
I <sub>H</sub>	T <sub>j</sub> = 25 °C			150	250	mA
IL	$T_j = 25$ °C, $R_G = 33 \Omega$			300	600	mA
$V_{GT}$	$T_j = 25$ °C, d.c.		2.5			V
I <sub>GT</sub>	$T_j = 25$ °C, d.c.		100			mA
$V_{GD}$	T <sub>j</sub> = 130 °C, d.c.				0.25	V
$I_{GD}$	T <sub>j</sub> = 130 °C, d.c.				4	mA
R <sub>th(j-c)</sub>	continuous DC	per chip			0.47	K/W
		per module			0.235	K/W
$R_{th(j-c)}$	sin. 180°	per chip			0.49	K/W
		per module			0.245	K/W
$R_{th(j-c)}$	rec. 120°	per chip			0.51	K/W
		per module			0.255	K/W
Module						
R <sub>th(c-s)</sub>	chip			0.22		K/W
	module			0.11		K/W
Ms	to heatsink M5		4.25		5.75	Nm
$M_t$	to terminals M5		2.55		3.45	Nm
а					5 * 9,81	m/s²
W				75		g



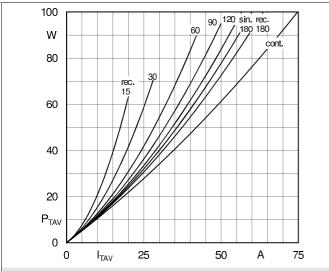


Fig. 1L: Power dissipation per thyristor/diode vs. on-state current

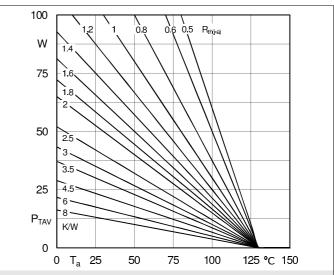


Fig. 1R: Max. power dissipation per chip vs. ambient temperature

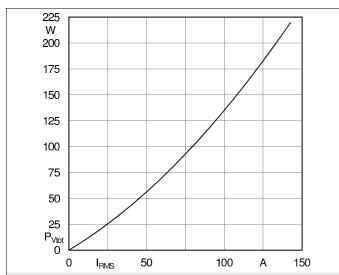


Fig. 2L: Max. power dissipation of one module vs. rms current

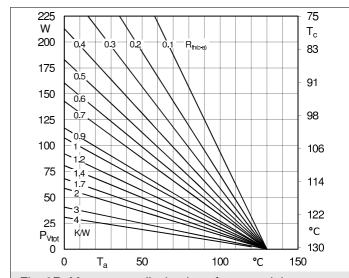


Fig. 2R: Max. power dissipation of one module vs. case temperature

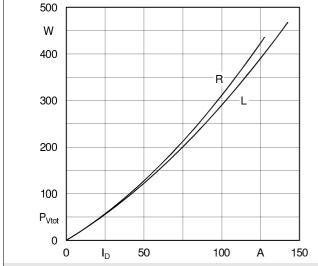


Fig. 3L: Max. power dissipation of two modules vs. direct current

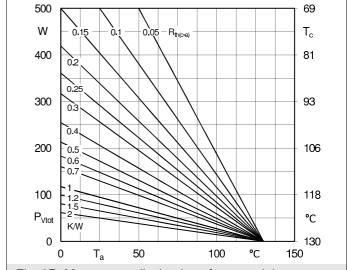


Fig. 3R: Max. power dissipation of two modules vs. case temperature

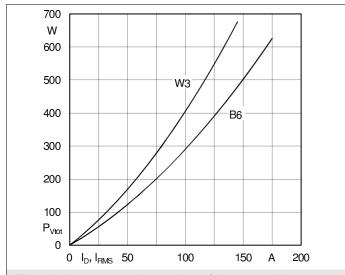


Fig. 4L: Max. power dissipation of three modules vs. direct current

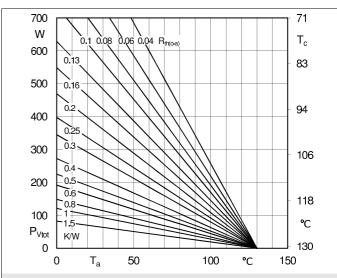


Fig. 4R: Max. power dissipation of three modules vs. case temperature

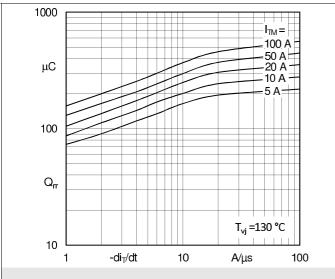


Fig. 5: Recovered charge vs. current decrease

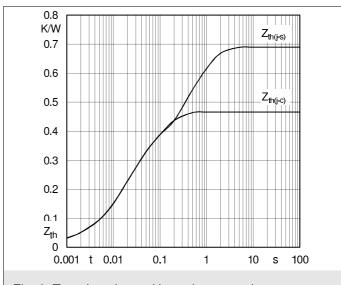


Fig. 6: Transient thermal impedance vs. time

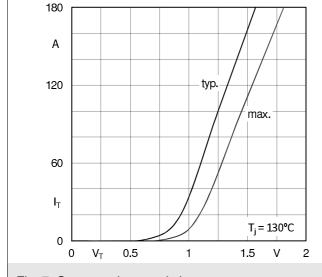


Fig. 7: On-state characteristics

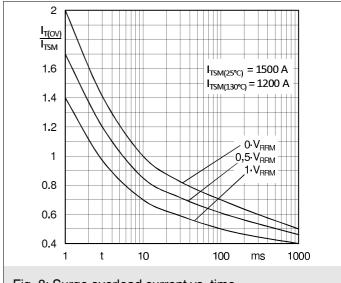
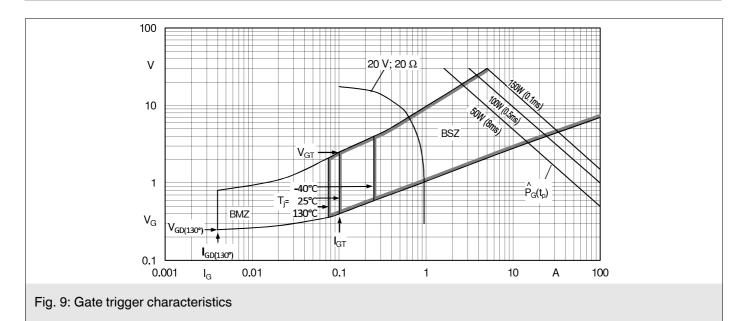
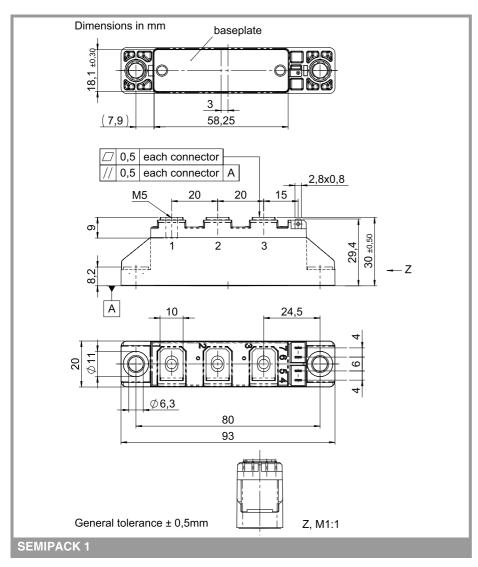
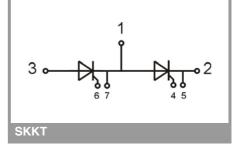


Fig. 8: Surge overload current vs. time







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

#### \*IMPORTANT INFORMATION AND WARNINGS

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